

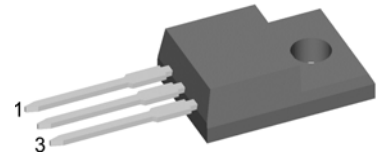
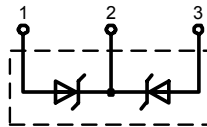
# Schottky

High Performance Schottky Diode  
 Low Loss and Soft Recovery  
 Common Cathode

$V_{RRM} = 60\text{ V}$   
 $I_{FAV} = 2 \times 10\text{ A}$   
 $V_F = 0.68\text{ V}$

Part number (Marking on product)

**DSA 20 C 60PN**



### Features / Advantages:

- Very low  $V_f$
- Extremely low switching losses
- Low  $I_{rm}$ -values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

### Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

### Package:

- TO-220FPAB
- Industry standard outline
  - Plastic overmolded tab for electrical isolation
  - Epoxy meets UL 94V-0
  - RoHS compliant

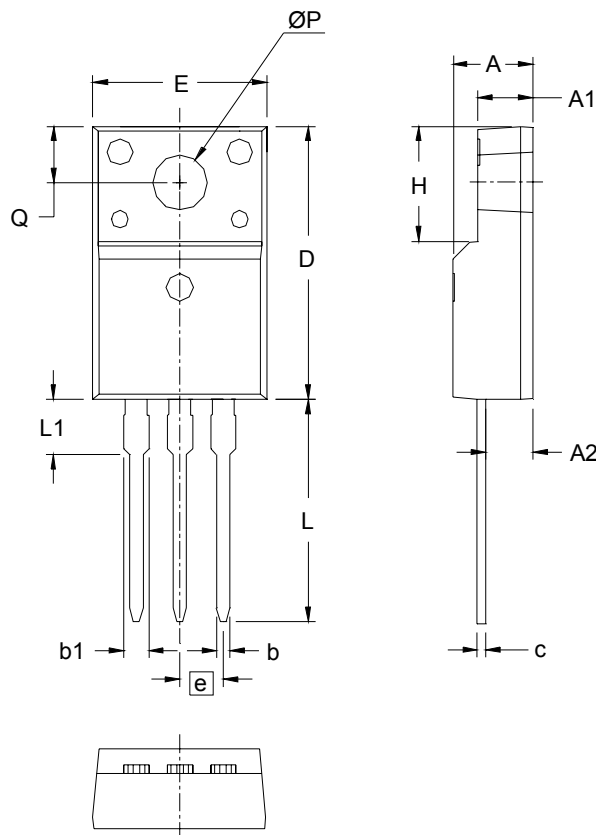
### Ratings

Symbol	Definition	Conditions	Ratings			Unit	
			min.	typ.	max.		
$V_{RRM}$	max. repetitive reverse voltage	$T_{VJ} = 25\text{ °C}$			60	V	
$I_R$	reverse current	$V_R = 60\text{ V}$			0.3	mA	
		$V_R = 60\text{ V}$			3	mA	
$V_F$	forward voltage	$I_F = 10\text{ A}$			0.85	V	
		$I_F = 20\text{ A}$			0.95	V	
		$I_F = 10\text{ A}$	$T_{VJ} = 125\text{ °C}$			0.68	V
		$I_F = 20\text{ A}$	$T_{VJ} = 125\text{ °C}$			0.78	V
$I_{FAV}$	average forward current	rectangular, $d = 0.5$			10	A	
$V_{F0}$	threshold voltage	} for power loss calculation only			0.44	V	
$r_F$	slope resistance				15	m $\Omega$	
$R_{thJC}$	thermal resistance junction to case				4.50	K/W	
$T_{VJ}$	virtual junction temperature		-55		175	°C	
$P_{tot}$	total power dissipation	$T_C = 25\text{ °C}$			35	W	
$I_{FSM}$	max. forward surge current	$t_p = 10\text{ ms (50 Hz), sine}$			100	A	
$C_j$	junction capacitance	$V_R = \text{ V}; f = 1\text{ MHz}$				pF	
$E_{AS}$	non-repetitive avalanche energy	$I_{AS} = \text{ A}; L = 100\text{ }\mu\text{H}$			tbd	mJ	
$I_{AR}$	repetitive avalanche current	$V_A = 1.5 \cdot V_R$ typ.; $f = 10\text{ kHz}$			tbd	A	

Symbol	Definition	Conditions	Ratings			Unit
			min.	typ.	max.	
$I_{RMS}$	RMS current	per pin*			35	A
$R_{thCH}$	thermal resistance case to heatsink			0.50		K/W
$M_D$	mounting torque		0.4		0.6	Nm
$F_c$	mounting force with clip		20		60	N
$T_{stg}$	storage temperature		-55		150	°C
<b>Weight</b>				2		g

\*  $I_{rms}$  is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

**Outlines TO-220FPAB**


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.177	.193	4.50	4.90
A1	.092	.108	2.34	2.74
A2	.101	.117	2.56	2.96
b	.028	.035	0.70	0.90
b1	.050	.058	1.27	1.47
c	.018	.024	0.45	0.60
D	.617	.633	15.67	16.07
E	.392	.408	9.96	10.36
e	.100 BSC		2.54 BSC	
H	.255	.271	6.48	6.88
L	.499	.523	12.68	13.28
L1	.119	.135	3.03	3.43
$\varnothing P$	.121	.129	3.08	3.28
Q	.126	.134	3.20	3.40